

### **Document Title**

4Mx4 bit Dynamic RAM with EDO Page Mode

### **Revision History**

Revision No	<u>History</u>	Draft Date	Remark
0A 0B	Initial Draft add Industrial grade parts	May 20,2001 October 17,2002	Preliminary



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# 4M x 4 (16-MBIT) DYNAMIC RAM WITH EDO PAGE MODE

#### **FEATURES**

- Extended Data-Out (EDO) Page Mode access cycle
- · TTL compatible inputs and outputs
- · Refresh Interval:
  - -- 2,048 cycles/32 ms
  - -- 4,096 cycles/64 ms
- Refresh Mode: RAS-Only, CAS-before-RAS (CBR), and Hidden
- JEDEC standard pinout
- Single power supply:
   5V ± 10% or 3.3V ± 10%
- Byte Write and Byte Read operation via two CAS

### **DESCRIPTION**

The ICSI 4400 Series is a 4,194,304 x 4-bit high-performance CMOS Dynamic Random Access Memory. These devices offer an accelerated cycle access called EDO Page Mode. EDO Page Mode allows 2,048 or 4096 random accesses within a single row with access cycle time as short as 20 ns per 4-bit word.

These features make the 4400 Series ideally suited for high-bandwidth graphics, digital signal processing, high-performance computing systems, and peripheral applications.

The 4400 Series is packaged in a 24-pin 300mil SOJ and a 24 pin TSOP-2

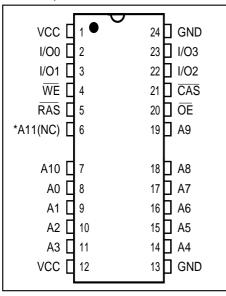
### PRODUCT SERIES OVERVIEW

Part No.	Refresh	Voltage
IS41C44002	2K	5V ± 10%
IS41C44004	4K	5V ± 10%
IS41LV44002	2K	3.3V ± 10%
IS41LV44004	4K	3.3V ± 10%

### KEY TIMING PARAMETERS

Parameter	-50	-60	Unit
RAS Access Time (trac)	50	60	ns
CAS Access Time (tcac)	13	15	ns
Column Address Access Time (taa)	25	30	ns
EDO Page Mode Cycle Time (tpc)	20	25	ns
Read/Write Cycle Time (trc)	84	104	ns

# PIN CONFIGURATION 24 Pin SOJ, TSOP-2



#### PIN DESCRIPTIONS

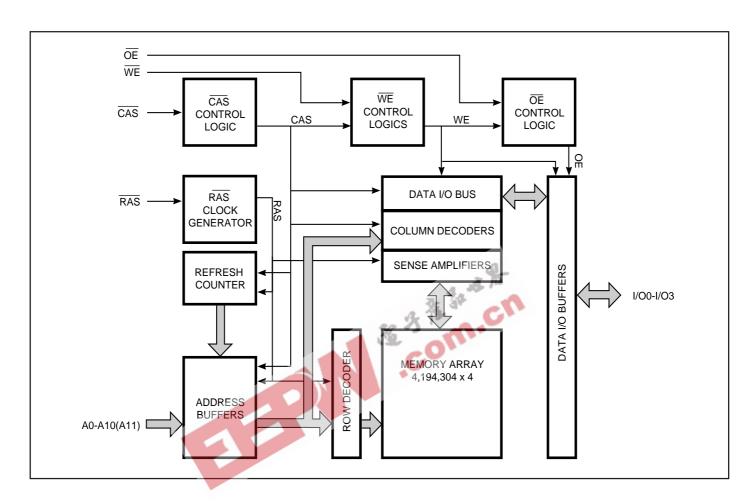
A0-A11	Address Inputs (4K Refresh)
A0-A10	Address Inputs (2K Refresh)
I/O0-3	Data Inputs/Outputs
WE	Write Enable
ŌĒ	Output Enable
RAS	Row Address Strobe
CAS	Column Address Strobe
Vcc	Power
GND	Ground
NC	No Connection

<sup>\*</sup> A11 is NC for 2K Refresh devices.

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### **FUNCTIONAL BLOCK DIAGRAM**



### **TRUTH TABLE**

Function		RAS	CAS	WE	ŌĒ	Address tr/tc	I/O
Standby		Н	Н	Χ	Χ	Χ	High-Z
Read		L	L	Н	L	ROW/COL	Dout
Write: Word (Early Write	<del>)</del>	L	L	L	Х	ROW/COL	DIN
Read-Write		L	L	H→L	L→H	ROW/COL	Dout, Din
EDO Page-Mode Read	1st Cycle:	L	H→L	Н	L	ROW/COL	Dout
	2nd Cycle:	L	$H{ ightarrow} L$	Н	L	NA/COL	Dout
EDO Page-Mode Write	1st Cycle:	L	$H{ ightarrow} L$	L	Χ	ROW/COL	DIN
	2nd Cycle:	L	$H{ ightarrow} L$	L	Χ	NA/COL	DIN
EDO Page-Mode	1st Cycle:	L	H→L	H→L	L→H	ROW/COL	Dout, Din
Read-Write	2nd Cycle:	L	$H{ ightarrow} L$	$H{ ightarrow} L$	$L{\rightarrow}H$	NA/COL	DOUT, DIN
Hidden Refresh	Read	$L\rightarrow H\rightarrow L$	L	Н	L	ROW/COL	Dout
	Write <sup>(1)</sup>	$L{\rightarrow}H{\rightarrow}L$	L	L	X	ROW/COL	Dout
RAS-Only Refresh		L	Н	Х	Х	ROW/NA	High-Z
CBR Refresh		H→L	L	Χ	Χ	Х	High-Z

#### Note:

1. EARLY WRITE only.



### **Functional Description**

The IC41C4400x and IC41LV4400x are CMOS DRAMs optimized for high-speed bandwidth, low power applications. During READ or WRITE cycles, each bit is uniquely addressed through the 11 or 12 address bits. These are entered 11 bits (A0-A10) at a time for the 2K refresh device or 12 bits (A0-A11) at a time for the 4K refresh device. The row address is latched by the Row Address Strobe (RAS). The column address is latched by the Column Address Strobe (CAS). RAS is used to latch the first nine bits and CAS is used the latter ten bits.

### **Memory Cycle**

A memory cycle is initiated by <u>bring RAS LOW</u> and it is terminated by returning both RAS and CAS HIGH. To ensures proper device operation and data integrity any memory cycle, once initiated, must not be ended or aborted before the minimum tras time has expired. A new cycle must not be initiated until the minimum precharge time trp, top has elapsed.

### **Read Cycle**

A read cycle is initiated by the falling edge of  $\overline{\text{CAS}}$  or  $\overline{\text{OE}}$ , whichever occurs last, while holding WE HIGH. The column address must be held for a minimum time specified by tar. Data Out becomes valid only when trac, taa, tcac and toea are all satisfied. As a result, the access time is dependent on the timing relationships between these parameters.

### Write Cycle

A write cycle is initiated by the falling edge of CAS and WE, whichever occurs last. The input data must be valid at or before the falling edge of CAS or WE, whichever occurs last.

### Refresh Cycle

To retain data, 2,048 refresh cycles are required in each 32 ms period, or 4,096 refresh cycles are required in each 64ms period. There are two ways to refresh the memory:

- By clocking each of the 2,048 row addresses (A0 through A10) or 4096 row addresses (A0 through A11) with RAS at least once every 32 ms or 64ms respectively. Any read, write, read-modify-write or RAS-only cycle refreshes the addressed row.
- Using a CAS-before-RAS refresh cycle. CAS-before-RAS refresh is activated by the falling edge of RAS, while holding CAS LOW. In CAS-before-RAS refresh cycle, an internal 9-bit counter provides the row addresses and the external address inputs are ignored.

CAS-before-RAS is a refresh-only mode and no data access or device selection is allowed. Thus, the output remains in the High-Z state during the cycle.

### Power-On

After application of the Vcc supply, an initial pause of 200 µs is required followed by a minimum of eight initialization cycles (any combination of cycles containing a RAS signal).

During power-on, it is recommended that  $\overline{RAS}$  track with Vcc or be held at a valid VIH to avoid current surges.





### **ABSOLUTE MAXIMUM RATINGS(1)**

Symbol	Parameters		Rating	Unit
VT	Voltage on Any Pin Relative to GND	5V	-1.0 to +7.0	V
		3.3V	-0.5 to +4.6	
Vcc	Supply Voltage	5V	-1.0 to +7.0	V
		3.3V	-0.5 to +4.6	
Іоит	Output Current		50	mA
Po	Power Dissipation		1	W
TA	Commercial Operation Temperature		0 to +70	°C
	Industrial Operation Temperature		-40 to +85	°C
Тѕтс	Storage Temperature		-55 to +125	°C

#### Note:

### RECOMMENDED OPERATING CONDITIONS (Voltages are referenced to GND.)

Symbol	Parameter	40	Min.	Тур.	Max.	Unit
Vcc	Supply Voltage	5V	4.5	5.0	5.5	V
		3.3V	3.0	3.3	3.6	
VIH	Input High Voltage	5V	2.4	_	Vcc + 1.0	V
		3.3V	2.0	_	Vcc + 0.3	
VIL	Input Low Voltage	5V	-1.0	_	0.8	V
		3.3V	-0.3	_	8.0	
TA	Commercial Ambient Temperature		0	_	70	°C
	Industrial Ambient Temperature		-40	_	85	°C

### CAPACITANCE(1,2)

Symbol	Parameter	Max.	Unit
CIN1	Input Capacitance: A0-A10(A11)	5	pF
CIN2	Input Capacitance: RAS, CAS, WE, OE	7	pF
Сю	Data Input/Output Capacitance: I/O0-I/O3	7	pF

#### Notes:

- 1. Tested initially and after any design or process changes that may affect these parameters.
- 2. Test conditions:  $T_A = 25^{\circ}C$ , f = 1 MHz.

Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.



### **ELECTRICAL CHARACTERISTICS(1)**

(Recommended Operating Conditions unless otherwise noted.)

Symbol	Parameter	Test Condition	Speed	Min.	Max.	Unit
lıL	Input Leakage Current	Any input 0V < VIN < Vcc Other inputs not under test = 0V		<b>–</b> 5	5	μΑ
lio	Output Leakage Current	Output is disabled (Hi-Z) 0V < Vout < Vcc		<b>-</b> 5	5	μΑ
Vон	Output High Voltage Level	IOH = -5.0 mA with $Vcc=5VIOH = -2.0$ mA with $Vcc=3.3V$		2.4	-	V
Vol	Output Low Voltage Level	IoL = 4.2 mA with Vcc=5V IoL = 2 mA with Vcc=3.3V		_	0.4	V
Icc1	Standby Current: TTL	RAS, CAS – VIH	5V 3.3V	_ _	2 0.5	mA
lcc2	Standby Current: CMOS	RAS, CAS > Vcc - 0.2V	5V 3.3V	_ _	1 0.5	mA
Icc3	Operating Current: Random Read/Write <sup>(2,3,4)</sup> Average Power Supply Current	RAS, CAS, Address Cycling, trc = trc (min.)	-50 -60	_	120 110	mA
Icc4	Operating Current: EDO Page Mode <sup>(2,3,4)</sup> Average Power Supply Current	RAS = VIL, CAS, Cycling tpc = tpc (min.)	-50 -60	_ _	90 80	mA
Icc5	Refresh Current: RAS-Only <sup>(2,3)</sup> Average Power Supply Current	RAS Cycling, CAS > VIH trc = trc (min.)	-50 -60	_ _	120 110	mA
Icc6	Refresh Current: CBR <sup>(2,3,5)</sup> Average Power Supply Current	RAS, CAS Cycling trc = trc (min.)	-50 -60	_ _	120 110	mA

### Notes:

<sup>1.</sup> An initial pause of 200 µs is required after power-up followed by eight  $\overline{RAS}$  refresh cycles ( $\overline{RAS}$ -Only or CBR) before proper device operation is assured. The eight  $\overline{RAS}$  cycles wake-up should be repeated any time the tree refresh requirement is exceeded.

<sup>2.</sup> Dependent on cycle rates.

<sup>3.</sup> Specified values are obtained with minimum cycle time and the output open.

<sup>4.</sup> Column-address is changed once each EDO page cycle.

<sup>5.</sup> Enables on-chip refresh and address counters.



### **AC CHARACTERISTICS**(1,2,3,4,5,6)

(Recommended Operating Conditions unless otherwise noted.)

			50	-(	60	
Symbol	Parameter	Min.	Max.	Min.	Max.	Units
trc	Random READ or WRITE Cycle Time	84	_	104	_	ns
trac	Access Time from RAS(6, 7)	_	50	_	60	ns
tcac	Access Time from CAS(6, 8, 15)	_	13	_	15	ns
taa	Access Time from Column-Address <sup>(6)</sup>	_	25	_	30	ns
tras	RAS Pulse Width	50	10K	60	10K	ns
trp	RAS Precharge Time	30	_	40	_	ns
tcas	CAS Pulse Width <sup>(23)</sup>	8	10K	10	10K	ns
tcp	CAS Precharge Time <sup>(9)</sup>	9	_	9	_	ns
tcsн	CAS Hold Time (21)	38	_	40	_	ns
trcd	RAS to CAS Delay Time(10, 20)	12	37	14	45	ns
tasr	Row-Address Setup Time	0	-	0	_	ns
trah	Row-Address Hold Time	8	- 43_	10	_	ns
tasc	Column-Address Setup Time(20)	0	4 2 14	0	_	ns
tcah	Column-Address Hold Time(20)	8	30-	10	_	ns
tar	Column-Address Hold Time (referenced to RAS)	30	W.C.	40	-	ns
trad	RAS to Column-Address Delay Time(11)	10	25	12	30	ns
tral	Column-Address to RAS Lead Time	25	_	30	_	ns
trpc	RAS to CAS Precharge Time	5	_	5	_	ns
trsh	RAS Hold Time	8	_	10	_	ns
trhcp	RAS Hold Time from CAS Precharge	30	_	35	_	ns
tclz	CAS to Output in Low-Z(15, 24)	0	_	0	_	ns
tcrp	CAS to RAS Precharge Time(21)	5	_	5	_	ns
top	Output Disable Time(19, 24)	3	15	3	15	ns
toe	Output Enable Time(15, 16)	_	12	_	15	ns
toed	Output Enable Data Delay (Write)	12	_	15	_	ns
toehc	OE HIGH Hold Time from CAS HIGH	5	_	5	_	ns
toep	OE HIGH Pulse Width	10	_	10	_	ns
toes	OE LOW to CAS HIGH Setup Time	5	_	5	_	ns
trcs	Read Command Setup Time(17, 20)	0	_	0	_	ns
trrh	Read Command Hold Time (referenced to RAS) <sup>(12)</sup>	0	-	0	-	ns
trch	Read Command Hold Time (referenced to CAS)(12, 17, 21)	0	_	0	-	ns
twch	Write Command Hold Time(17)	8	_	10	_	ns
twcr	Write Command Hold Time (referenced to RAS) <sup>(17)</sup>	40	_	50	-	ns
twp	Write Command Pulse Width(17)	8	_	10	_	ns
twpz	WE Pulse Widths to Disable Outputs	7	_	7	_	ns
trwL	Write Command to RAS Lead Time(17)	13	_	15	_	ns
tcwL	Write Command to CAS Lead Time(17, 21)	8	_	10	_	ns
twcs	Write Command Setup Time(14, 17, 20)	0	_	0	_	ns
tdhr	Data-in Hold Time (referenced to RAS)	39	_	39	_	ns



### AC CHARACTERISTICS (Continued)(1,2,3,4,5,6)

(Recommended Operating Conditions unless otherwise noted.)

			-50		-60	
Symbol	Parameter	Min.	Max.	Min.	Max.	Units
tach	Column-Address Setup Time to CAS Precharge during WRITE Cycle	15	_	15	-	ns
tоен	OE Hold Time from WE during READ-MODIFY-WRITE cycle <sup>(18)</sup>	8	-	10	-	ns
tos	Data-In Setup Time(15, 22)	0	_	0	_	ns
tон	Data-In Hold Time(15, 22)	8	_	10	_	ns
trwc	READ-MODIFY-WRITE Cycle Time	108	_	133	_	ns
trwd	RAS to WE Delay Time during READ-MODIFY-WRITE Cycle(14)	64	_	77	_	ns
tcwp	CAS to WE Delay Time(14, 20)	26	_	32	_	ns
<b>t</b> awd	Column-Address to WE Delay Time(14)	39	_	47	_	ns
tpc	EDO Page Mode READ or WRITE Cycle Time	20	- 49	25	_	ns
trasp	RAS Pulse Width in EDO Page Mode	50	100K	60	100K	ns
<b>t</b> CPA	Access Time from CAS Precharge(15)	X	30	=	35	ns
<b>t</b> PRWC	EDO Page Mode READ-WRITE Cycle Time	56	Othi	68	-	ns
tсон	Data Output Hold after CAS LOW	5	_	5	_	ns
toff	Output Buffer Turn-Off Delay from CAS or RAS(13,15,19,24)	0	12	0	15	ns
twnz	Output Disable Delay from WE	3	10	3	10	ns
tcsr	CAS Setup Time (CBR REFRESH)(20, 25)	5	_	5	_	ns
tchr	CAS Hold Time (CBR REFRESH)(21, 25)	8	_	10	_	ns
tord	OE Setup Time prior to RAS during HIDDEN REFRESH Cycle	0	_	0	_	ns
tref	Auto Refresh Period 2,048 Cycles	_	32	_	32	ms
	4,096 Cycles	_	64	_	64	
tτ	Transition Time (Rise or Fall)(2, 3)	1	50	1	50	ns

### **AC TEST CONDITIONS**

Output load: Two TTL Loads and 50 pF Input timing reference levels: VIH = 2.4V, VIL = 0.8V

Output timing reference levels: VoH = 2.0V, VoL = 0.8V

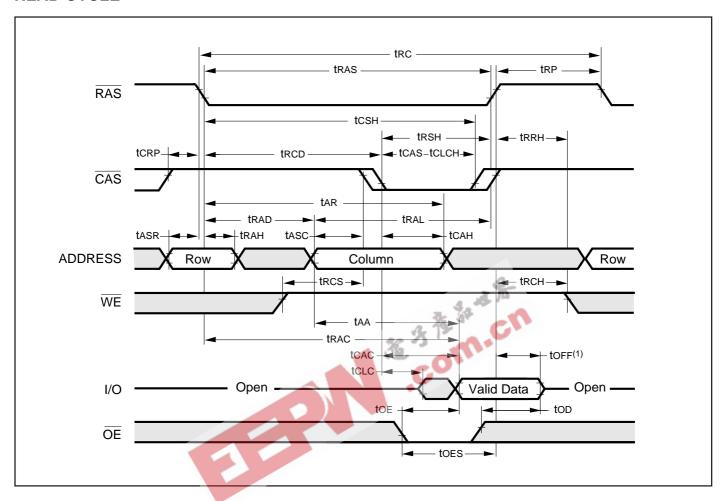


#### Notes:

- 1. An initial pause of 200 µs is required after power-up followed by eight  $\overline{\text{RAS}}$  refresh cycle ( $\overline{\text{RAS}}$ -Only or CBR) before proper device operation is assured. The eight  $\overline{\text{RAS}}$  cycles wake-up should be repeated any time the tree refresh requirement is exceeded.
- 2. V<sub>I</sub>H (MIN) and V<sub>I</sub>L (MAX) are reference levels for measuring timing of input signals. Transition times, are measured between V<sub>I</sub>H and V<sub>I</sub>L (or between V<sub>I</sub>L and V<sub>I</sub>H) and assume to be 1 ns for all inputs.
- 3. In addition to meeting the transition rate specification, all input signals must transit between V<sub>IH</sub> and V<sub>IL</sub> (or between V<sub>IL</sub> and V<sub>IH</sub>) in a monotonic manner.
- 4. If  $\overline{CAS}$  and  $\overline{RAS} = V_{IH}$ , data output is High-Z.
- 5. If  $\overline{CAS} = V_{IL}$ , data output may contain data from the last valid READ cycle.
- 6. Measured with a load equivalent to one TTL gate and 50 pF.
- 7. Assumes that tRCD < tRCD (MAX). If tRCD is greater than the maximum recommended value shown in this table, tRAC will increase by the amount that tRCD exceeds the value shown.
- 8. Assumes that trcd > trcd (MAX).
- 9. If  $\overline{\text{CAS}}$  is LOW at the falling edge of  $\overline{\text{RAS}}$ , data out will be maintained from the previous cycle. To initiate a new cycle and clear the data output buffer,  $\overline{\text{CAS}}$  and  $\overline{\text{RAS}}$  must be pulsed for tcp.
- 10. Operation with the tRCD (MAX) limit ensures that tRAC (MAX) can be met. tRCD (MAX) is specified as a reference point only; if tRCD is greater than the specified tRCD (MAX) limit, access time is controlled exclusively by tCAC.
- 11. Operation within the trad (MAX) limit ensures that trad (MAX) can be met. trad (MAX) is specified as a reference point only; if trad is greater than the specified trad (MAX) limit, access time is controlled exclusively by taa.
- 12. Either trich or trich must be satisfied for a READ cycle.
- 13. toff (MAX) defines the time at which the output achieves the open circuit condition; it is not a reference to Voh or Vol.
- 14. twcs, trwb, tawb and tcwb are restrictive operating parameters in LATE WRITE and READ-MODIFY-WRITE cycle only. If twcs > twcs (MIN), the cycle is an EARLY WRITE cycle and the data output will remain open circuit throughout the entire cycle. If trwb > trwb (MIN), tawb > tawb (MIN) and tcwb > tcwb (MIN), the cycle is a READ-WRITE cycle and the data output will contain data read from the selected cell. If neither of the above conditions is met, the state of I/O (at access time and until CAS and RAS or OE go back to Vih) is indeterminate. OE held HIGH and WE taken LOW after CAS goes LOW result in a LATE WRITE (OE-controlled) cycle.
- 15. Output parameter (I/O) is referenced to corresponding CAS input.
- 16. During a READ cycle, if  $\overline{OE}$  is LOW then taken HIGH before  $\overline{CAS}$  goes HIGH, 1/O goes open. If  $\overline{OE}$  is tied permanently LOW, a LATE WRITE or READ-MODIFY-WRITE is not possible.
- 17. Write command is defined as WE going low.
- 18. LATE WRITE and READ-MODIFY-WRITE cycles must have both top and toeh met (OE HIGH during WRITE cycle) in order to ensure that the output buffers will be open during the WRITE cycle. The I/Os will provide the previously written data if CAS remains LOW and OE is taken back to LOW after toeh is met.
- 19. The I/Os are in open during READ cycles once top or toff occur.
- 20. Determined by falling edge of CAS.
- 21. Determined by rising edge of CAS.
- 22. These parameters are referenced to CAS leading edge in EARLY WRITE cycles and WE leading edge in LATE WRITE or READ-MODIFY-WRITE cycles.
- 23. CAS must meet minimum pulse width.
- 24. The 3 ns minimum is a parameter guaranteed by design.
- 25. Enables on-chip refresh and address counters.



### **READ CYCLE**

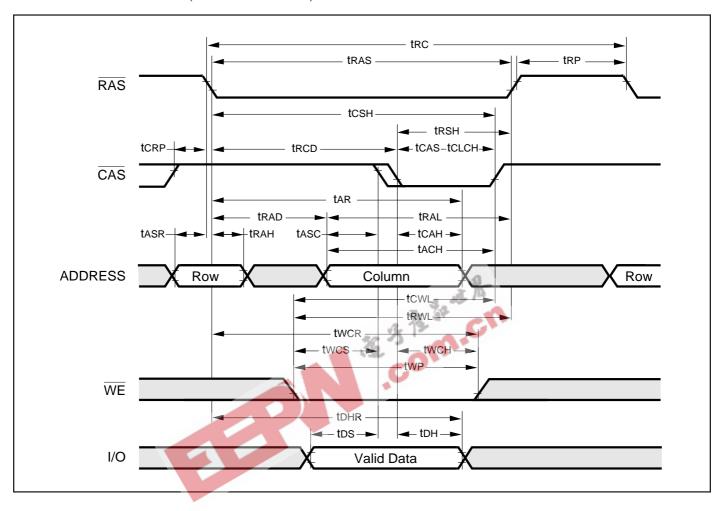


#### Note:

1. toff is referenced from rising edge of RAS or CAS, whichever occurs last.

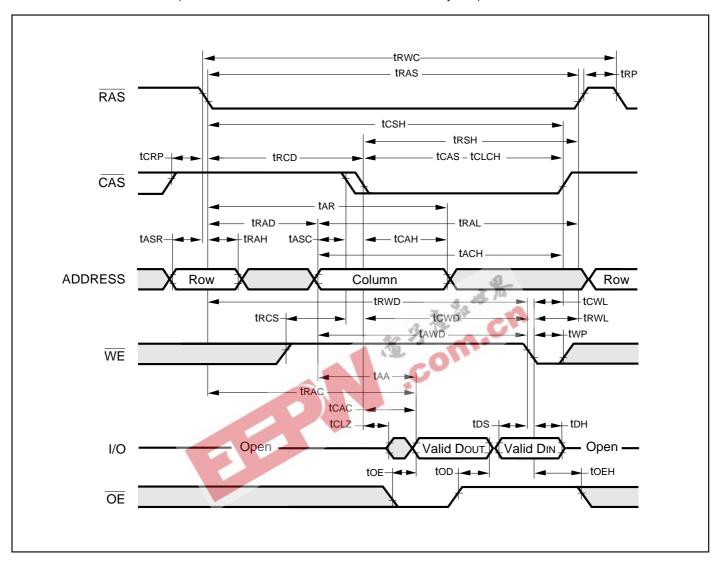


### **EARLY WRITE CYCLE** (OE = DON'T CARE)



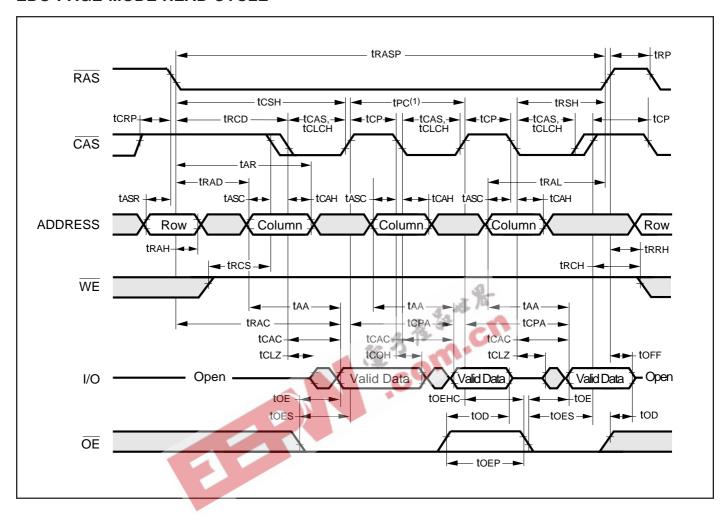


### **READ WRITE CYCLE** (LATE WRITE and READ-MODIFY-WRITE Cycles)





### **EDO-PAGE-MODE READ CYCLE**

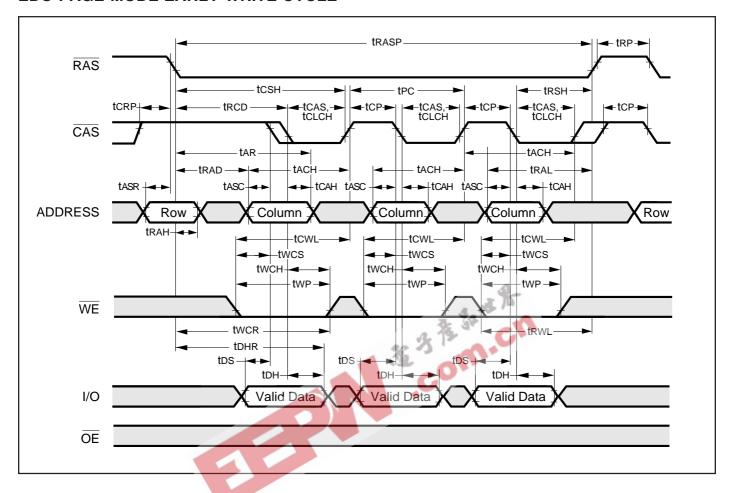


### Note:

1. tPC can be measured from falling edge of  $\overline{CAS}$  to falling edge of  $\overline{CAS}$ , or from rising edge of  $\overline{CAS}$  to rising edge of  $\overline{CAS}$ . Both measurements must meet the tPC specifications.

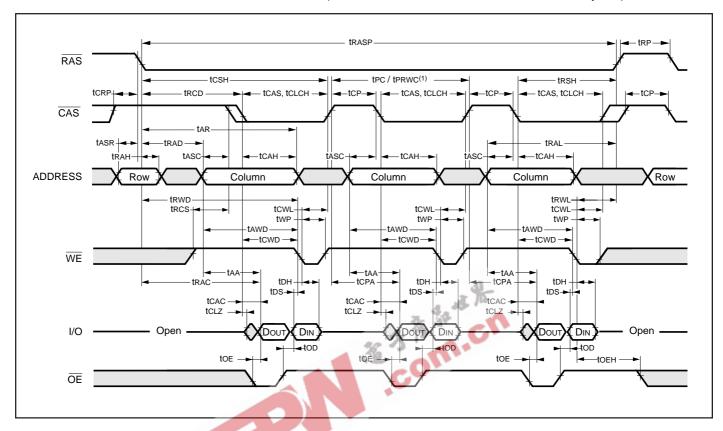


### **EDO-PAGE-MODE EARLY-WRITE CYCLE**





### EDO-PAGE-MODE READ-WRITE CYCLE (LATE WRITE and READ-MODIFY WRITE Cycles)

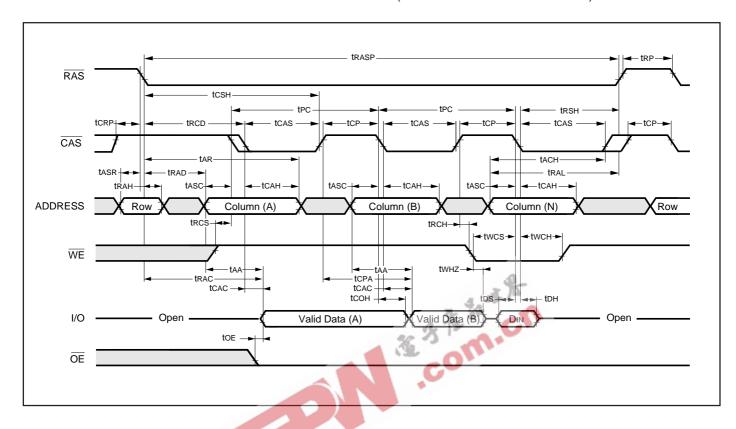


#### Note:

1. tPC can be measured from falling edge of CAS to falling edge of CAS, or from rising edge of CAS to rising edge of CAS. Both measurements must meet the tPC specifications.



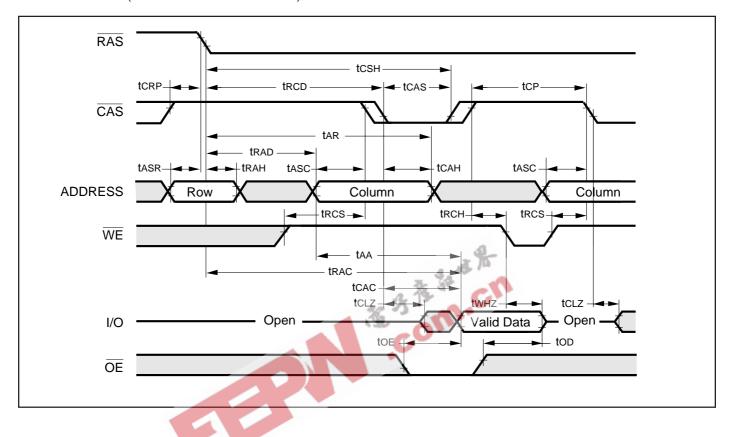
### EDO-PAGE-MODE READ-EARLY-WRITE CYCLE (Psuedo READ-MODIFY WRITE)



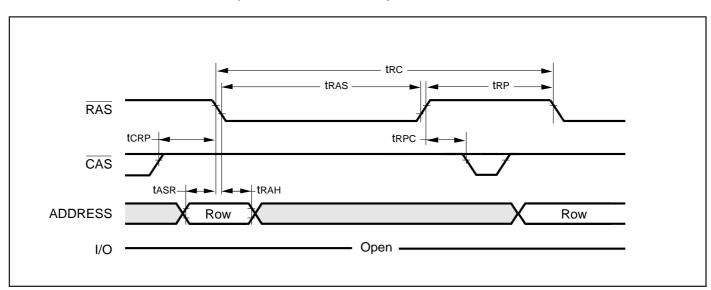


### **AC WAVEFORMS**

### **READ CYCLE** (With WE-Controlled Disable)

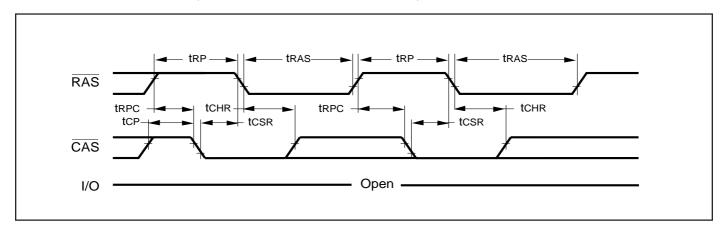


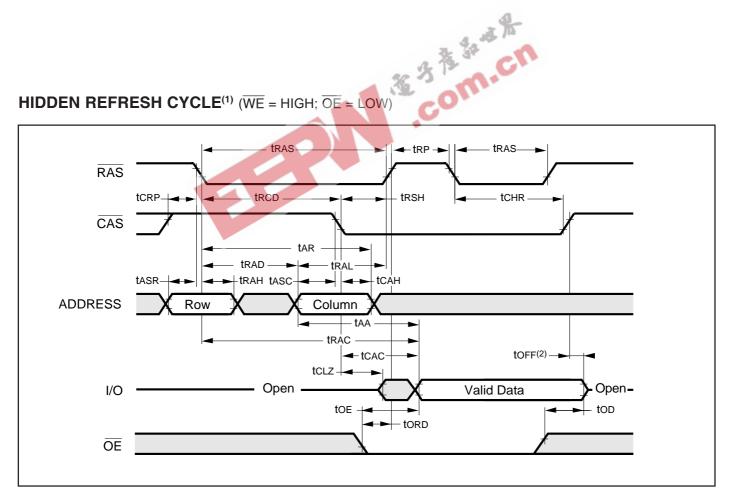
## $\overline{\text{RAS}}\text{-}\text{ONLY REFRESH CYCLE }(\overline{\text{OE}}, \overline{\text{WE}} = \text{DON'T CARE})$





### **CBR REFRESH CYCLE** (Addresses; WE, OE = DON'T CARE)





- 1. A Hidden Refresh may also be performed after a Write Cycle. In this case,  $\overline{WE} = LOW$  and  $\overline{OE} = HIGH$ .
- 2. toff is referenced from rising edge of  $\overline{RAS}$  or  $\overline{CAS}$ , whichever occurs last.



### **ORDERING INFORMATION**

Commercial Range: 0°C to 70°C

Voltage: 5V

Speed (ns)	Order Part No.	Refresh	Package
50	IC41C44002-50J	2K	300mil SOJ
50	IC41C44002-50T	2K	300mil TSOP-2
60	IC41C44002-60J	2K	300-mil SOJ
60	IC41C44002-60T	2K	300mil TSOP-2

Speed (ns)	Order Part No.	Refresh	Package
50	IC41C44004-50J	4K	300mil SOJ
50	IC41C44004-50T	4K	300mil TSOP-2
60	IC41C44004-60J	4K	300mil SOJ
60	IC41C44004-60T	4K	300mil TSOP-2

60	IC41C44004-60T	4K	300mil TSOP-2
Voltage: 3.	3V	26 为书	W.CU
Speed (ns)	Order Part No.	Refresh	Package
50	IC41LV44002-50J	2K	300mil SOJ
50	IC41LV44002-50T	2K	300mil TSOP-2
60	IC41LV44002-60J	2K	300mil SOJ
60	IC41LV44002-60T	2K	300mil TSOP-2

Speed (ns)	Order Part No.	Refresh	Package
50	IC41LV44004-50J	4K	300mil SOJ
50	IC41LV44004-50T	4K	300mil TSOP-2
60	IC41LV44004-60J	4K	300mil SOJ
60	IC41LV44004-60T	4K	300mil TSOP-2



### **ORDERING INFORMATION**

Industrial Range: -40°C to 85°C

Voltage: 5V

Speed (ns)	Order Part No.	Refresh	Package
50	IC41C44002-50JI	2K	300mil SOJ
50	IC41C44002-50TI	2K	300mil TSOP-2
60	IC41C44002-60JI	2K	300-mil SOJ
60	IC41C44002-60TI	2K	300mil TSOP-2

Speed (ns)	Order Part No.	Refresh	Package
50	IC41C44004-50JI	4K	300mil SOJ
50	IC41C44004-50TI	4K	300mil TSOP-2
60	IC41C44004-60JI	4K	300mil SOJ
60	IC41C44004-60TI	4K	300mil TSOP-2

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IC41C44004-6011	4K	300mil TSOP-2
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Order Part No.	Refresh	Package
IC41LV44002-50JI	2K	300mil SOJ
IC41LV44002-50TI	2K	300mil TSOP-2
IC41LV44002-60JI	2K	300mil SOJ
		300mil TSOP-2
	IC41LV44002-50JI IC41LV44002-50TI IC41LV44002-60JI	Order Part No. Refresh IC41LV44002-50JI 2K IC41LV44002-50TI 2K

Speed (ns)	Order Part No.	Refresh	Package
50	IC41LV44004-50JI	4K	300mil SOJ
50	IC41LV44004-50TI	4K	300mil TSOP-2
60	IC41LV44004-60JI	4K	300mil SOJ
60	IC41LV44004-60TI	4K	300mil TSOP-2



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